

# 3A, 50V - 1000V Surface Mount Rectifier

#### **FEATURES**

- Glass passivated chip junction
- Ideal for automated placement
- Low forward voltage drop
- High current capability
- High surge current capability
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

### **MECHANICAL DATA**

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.21 g (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
I <sub>F(AV)</sub>	3	Α			
$V_{RRM}$	50 - 1000	V			
I <sub>FSM</sub>	100	Α			
$T_{JMAX}$	150	°C			
Package	DO-214AB (SMC)				
Configuration	Single die				

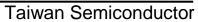




DO-214AB (SMC)

PARAMETER	SYMBOL	S3A	S3B	S3D	S3G	S3J	S3K	S3M	UNIT
Marking code on the device		S3A	S3B	S3D	S3G	S3J	S3K	S3M	
Repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Reverse voltage, total rms value	V <sub>R(RMS)</sub>	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Forward current	I <sub>F(AV)</sub> 3			Α					
Surge peak forward current, 8.3 ms single half sine-wave uperimposed on rated load per diode	I <sub>FSM</sub>	100			А				
Junction temperature	TJ	- 55 to +150			°C				
Storage temperature	T <sub>STG</sub>	T <sub>STG</sub> - 55 to +150			°C				

1





THERMAL PERFORMANCE						
PARAMETER	SYMBOL	LIMIT	UNIT			
Junction-to-lead thermal resistance per diode	R <sub>eJL</sub>	13	°C/W			
Junction-to-ambient thermal resistance per diode	$R_{\Theta JA}$	47	°C/W			

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	TYP.	MAX.	UNIT	
Forward voltage per diode (1)	I <sub>F</sub> = 3A, T <sub>J</sub> = 25°C	V <sub>F</sub>	-	1.15	V	
Reverse current @ rated V <sub>R</sub> per diode <sup>(2)</sup>	T <sub>J</sub> = 25°C		-	10	μA	
Reverse current @ rated v <sub>R</sub> per diode	T <sub>J</sub> = 125°C	- I <sub>R</sub>	-	250	μA	
Junction capacitance	1 MHz, V <sub>R</sub> =4.0V	CJ	60	-	pF	
Reverse recovery time	I <sub>F</sub> =0.5A , I <sub>R</sub> =1.0A I <sub>RR</sub> =0.25A	t <sub>rr</sub>	1500	-	ns	

### Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

PRDERING INFORMATION						
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING	
		R7		SMC	850 / 7" Plastic reel	
	R6		SMC	3,000 / 13" Paper reel		
	S3x (Note 1)	M6	G	SMC	3,000 / 13" Plastic reel	
(NOIE 1)		V7		Matrix SMC	850 / 7" Plastic reel	
		V6		Matrix SMC	3,000 / 13" Plastic reel	

### Note:

1. "x" defines voltage from 50V (S3A) to 1000V (S3M)

EXAMPLE						
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION	
S3AHR7G	S3A	H	R7	G	AEC-Q101 qualified Green compound	

2



0

25

50

### **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve

3.5

(V) 3

2.5

DAWAY

1.5

RESISTIVE OR INDUCTIVE LOAD

Fig.3 Typical Reverse Characteristics

75

LEAD TEMPERATURE (°C)

100

125

150

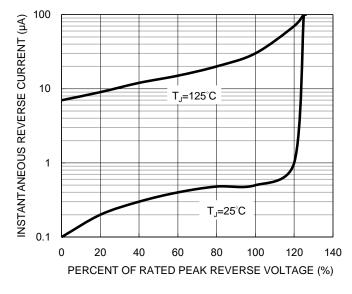
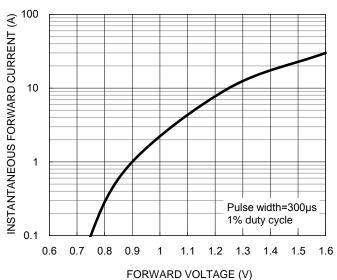


Fig.4 Typical Forward Characteristics





### **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

Fig.5 Maximum Non-repetitive Forward Surge Current

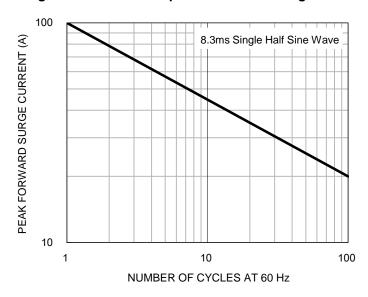
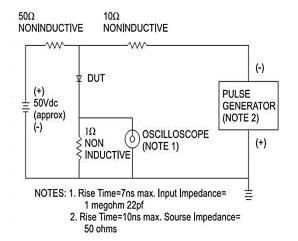
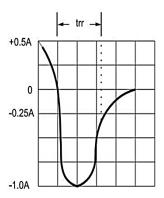


Fig.6 Reverse Recovery Time Characteristic And Test Circuit Diagram

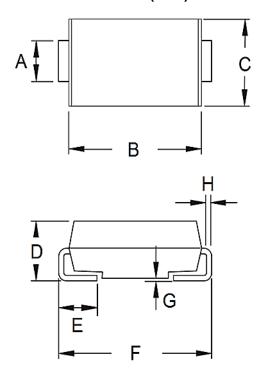






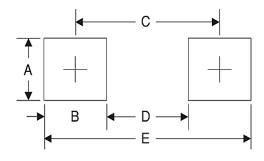
# **PACKAGE OUTLINE DIMENSIONS**

## DO-214AB (SMC)



DIM.	Unit (mm)		Unit (inch)	
DIIVI.	Min	Max	Min	Max
Α	2.90	3.20	0.114	0.126
В	6.60	7.11	0.260	0.280
С	5.59	6.22	0.220	0.245
D	2.00	2.62	0.079	0.103
Е	1.00	1.60	0.039	0.063
F	7.75	8.13	0.305	0.320
G	0.10	0.20	0.004	0.008
Н	0.15	0.31	0.006	0.012

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
А	3.30	0.130
В	2.50	0.098
С	6.80	0.268
D	4.40	0.173
Е	9.40	0.370

## **MARKING DIAGRAM**



P/N =Marking Code

G =Green Compound

YW =Date Code F =Factory Code



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